











Test & Measurement Viewpoint Challenges in testing 5G components



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Where EXFO helps the 5G boom, from lab to live



LAB, R&D AND FACTORY TESTING

- PIC Testing
- Passive component
- 400G and beyond
- Transceivers
- Load testing and simulation



- Broadband access
- FTTx/PON
- Residential services
- · Data centers
- Small cell rollout



VALIDATE SERVICE READINESS

- 4G/5G transport backhaul, fronthaul X-haul
- Service and infrastructure
- Capacity certification
- Orchestration



END-TO-END MONITORING

- Layer 0 to 7
- Fiber, RAN, RF and core monitoring
- NFV service assurance
- Active testing and passive monitoring
- Network, service and subscribers analytics



TROUBLESHOOTING

• RE and RAN

optimization

INSIGHTS AND

 Dynamic topology, advanced use cases and automated troubleshooting

---- Design and test ----

Build and validate --

Operate, assure and transform



5G Product Portfolio





































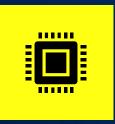






5G Component Testing

PIC-based components



Evolving PIC technology Active

Passive Hybrid

Thousands of devices 100s comp/chip

Complex test stations Functional Parametric Passive optical components



Complex devices

Diversity of components (M inputs, N outputs)

Test Speed vs Integrity

Test reliability vs CAPEX

New-generation Optical transceivers



Diversity of transceivers

Multiple tech Higher speed Tunability

Support form factors
Ouick

Extensive Reliable



Converged 5G xHaul transport



Ubiquitous transport equipment for 5G New structure New equipments

Multiple protocols

Co-existence 5G / 4G

Ultra-high reliability







PIC-based components for 5G



CHALLENGE | SOLUTION | RESULTS

Active and passive component measurement

Characterization of thousands of components per wafer

Multivendor and complex test stations

Testing at different stages: wafer level, die level, packaging, quality assurance







PIC-based components for 5G



CHALLENGE | SOLUTION | RESULTS

OSA20 & CTP10

Active and passive optical component testing

Swept optical testing provides fast acquisition with picometer resolution and accuracy

Full remote control via SCPI commands

Wafer-level and final testing after packaging







PIC-based components for 5G



CHALLENGE | SOLUTION | RESULTS

OSA20 for transceiver testing: measurement of key parameters such as central wavelength, SMSR and OSNR

CTP10 for passive component testing: IL, RL, PDL, incl. AWG or ring resonators in record time.

High dynamic range measurement in a single scan, ensuring fast and reliable results

Proven integrations with several probe station manufacturers

Consistent measurements using the same test instruments throughout all the manufacturing stages

CTP10 analysis results



